

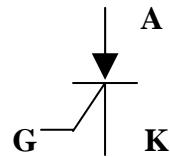


## 0.8A SCRs

Sensitive Gate / Silicon Controlled Rectifiers

### Main features

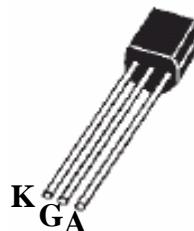
Symbol	Value	Unit
$I_{T(RMS)}$	0.8A	A
$V_{DRM}/V_{RRM}$	950	V
$I_{GT(Q1)}$	200	uA



### DESCRIPTION

These devices are intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

Weight : 0.22 gram



TO92

### Absolute maximum ratings

Symbol	Parameter	Value	Unit
$I_{T(RMS)}$	RMS on-state current ( 180° conduction angle )	0.8	A
$I_{TSM}$	Non repetitive surge on-state current ( 1/2 Cycle, Sine Wave , $T_j$ initial=25°C )	$F = 50\text{Hz}$ $t = 10\text{ms}$	8
		$F = 60\text{Hz}$ $t = 8.3\text{ms}$	9
$I^2t$	$I^2t$ Value for fusing	$t_p = 10\text{ms}$	$\text{A}^2\text{s}$
$dl/dt$	Critical rate of rise of on-state current $I_G = 10\text{mA}$ $di_G = 0.1\text{A/us}$	30	$\text{A/us}$
$I_{GM}$	Peak gate current	1	A
$P_{G(AV)}$	Average gate power dissipation	0.1	W
$T_{stg}$ $T_j$	Storage junction temperature range Operating junction temperature range	-40 to +150 -40 to +110	°C

### Electrical characteristics ( $T_j = 25^\circ\text{C}$ , unless otherwise specified)

Symbol	Test conditions		MCR100-8A	Unit
$V_{\text{DRM}}, V_{\text{RRM}}$			950	V
$I_{\text{GT}}(1)$	$V_D = 7\text{V}$ $R_L = 100\Omega$	MAX.	200	uA
$V_{\text{GT}}$		MAX.	0.8	V
$I_H(2)$	$V_D = 7\text{V}$ , $I_{\text{GT}} = 0.5 \text{ mA}$ $R_{\text{GK}} = 1\text{k}\Omega$	MAX.	5	mA
$I_L$	$V_D = 7\text{V}$ , $I_{\text{GT}} = 0.5 \text{ mA}$ $R_{\text{GK}} = 1\text{k}\Omega$	MAX.	6	mA
dV/dt (2)	$V_D = 67\% V_{\text{DRM}}$ $R_{\text{GK}} = 1\text{k}\Omega$ $T_j = 110^\circ\text{C}$	MIN.	50	V/us

### Static characteristics

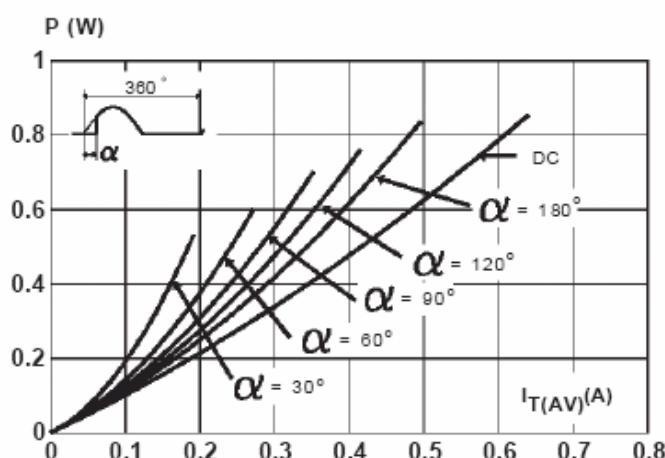
Symbol	Test conditions			Value	Unit
$V_T(2)$	$I_{\text{TM}} = 1.2\text{A}$	$t_p = 380 \mu\text{s}$	$T_j = 25^\circ\text{C}$	1.55	V
$I_{\text{DRM}}$	$V_{\text{DRM}}=V_{\text{RRM}}$		$T_j = 25^\circ\text{C}$	10	uA
$I_{\text{RRM}}$			$T_j = 110^\circ\text{C}$	0.2	mA

### Thermal resistance

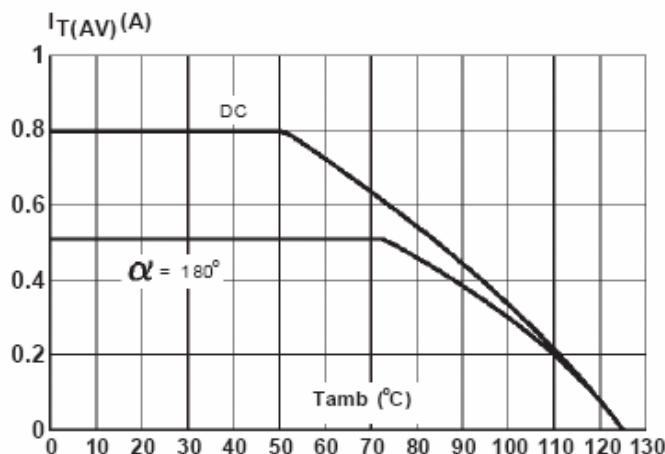
Symbol	Parameter	Value	Unit
$R_{\text{th(j-l)}}$	Junction to lead for DC	80	$^\circ\text{C}/\text{W}$
$R_{\text{th(j-a)}}$	Junction to ambient	150	$^\circ\text{C}/\text{W}$



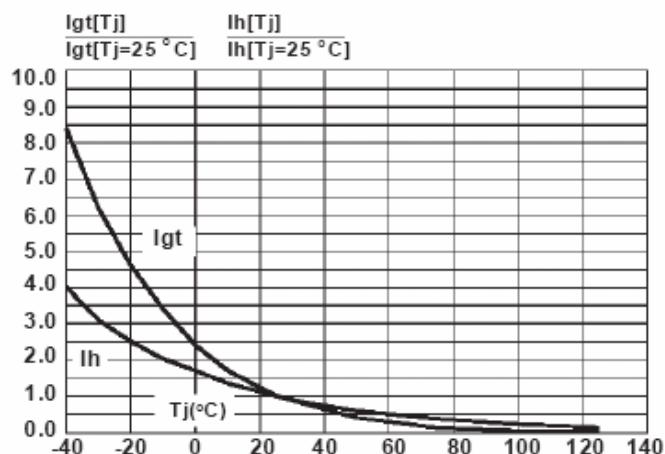
**Fig.1** : Maximum average power dissipation versus average on-state current.



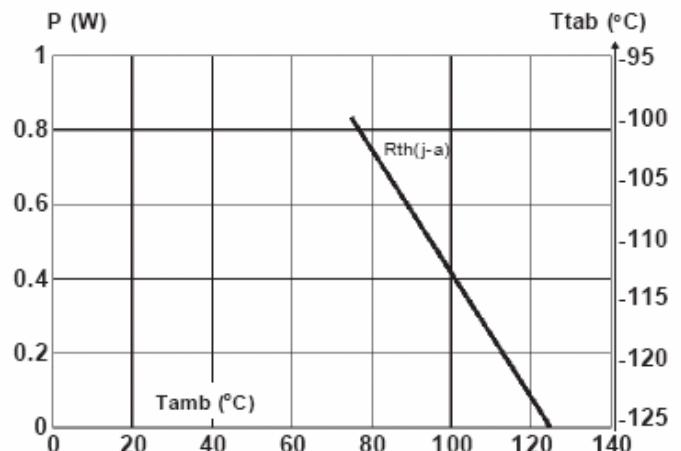
**Fig.3** : Average on-state current versus tab temperature.



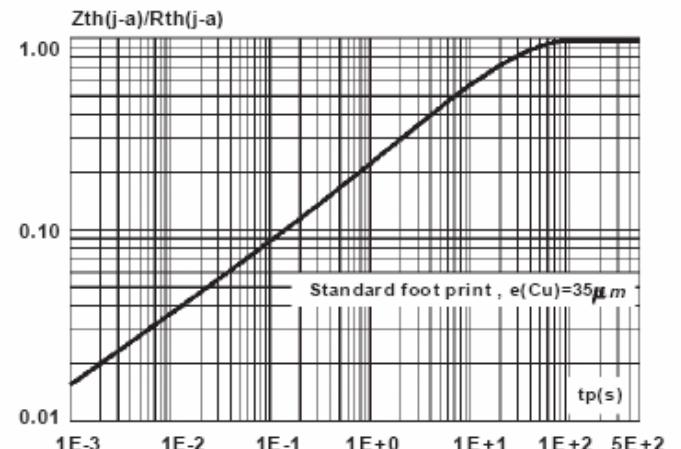
**Fig.5** : Relative variation of gate trigger current and holding current versus junction temperature.



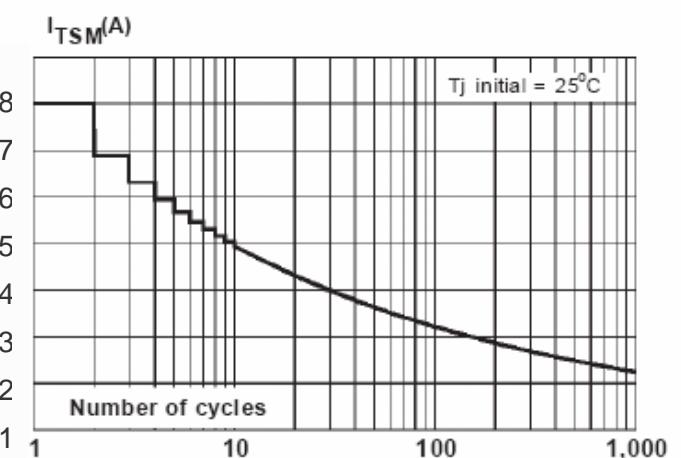
**Fig.2** : Correlation between maximum average power dissipation and maximum allowable temperature (Tamb and Ttab).



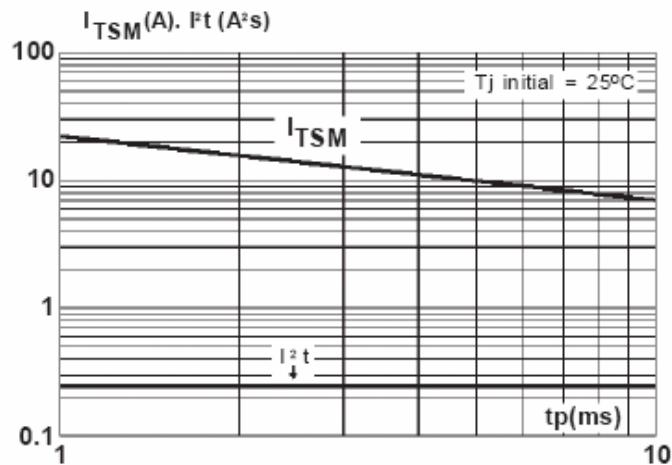
**Fig.4** : Relative variation of thermal impedance junction to ambient versus pulse duration.



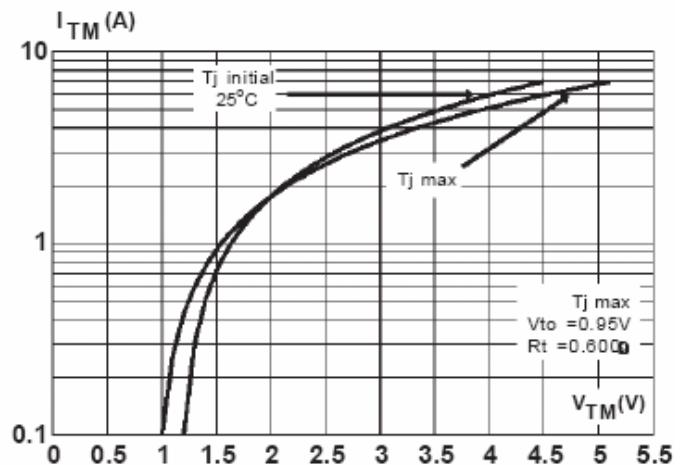
**Fig.6** : Non repetitive surge peak on-state current versus number of cycles.



**Fig.7** : Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t_p \geq 10\text{ms}$ , and corresponding value of  $I^2 t$ .



**Fig.8** : On-state characteristics (maximum values).



**Fig.9** : Relative variation of holding current versus gate-cathode resistance (typical values).

